# PERFORMANCE SPECIFICATIONS

### **ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Conditions	Min.	Тур.	Max	Unit
Supply voltage	V <sub>DD</sub>		-0.3		+3.6	V
Storage temperature	Ts		-40		+85	°C
Overpressure	P <sub>max</sub>	ISO6425			30	bar
Maximum Soldering Temperature	T <sub>max</sub>	40 sec max			250	°C
ESD rating		Human Body Model	-2		2	kV
Latch up		JEDEC standard No 78	-100		+100	mA

### **ELECTRICAL CHARACTERISTICS**

Parameter	Symbol	Conditions	Min.	Тур.	Max	Unit
Operating Supply voltage	V <sub>DD</sub>		2.2	3.0	+3.6	V
Operating Temperature	Т		-20	+25	+85	°C
Output Word				24		bit
Supply current (1 sample per sec.)	I <sub>DD</sub>	Depending on OSR	0.9		12.5	μA
Peak supply current		during conversion		1.4		mA
Standby supply current		at 25°c		0.02	0.14	μA
VDD Capacitor		From VDD to GND	100	470		nF

### ANALOG DIGITAL CONVERTER (ADC)

Parameter	Symbol	Conditions	S	Min.	Тур.	Max	Unit
Output Word					24		bit
Conversion time		OSR	4096	7.40	8.22	9.04	
			2048	3.72	4.13	4.54	
	t <sub>c</sub>		1024	1.88	2.08	2.28	ms
			512	0.95	1.06	1.17	
			256	0.48	0.54	0.60	



### **PERFORMANCE SPECIFICATIONS (CONTINUED)**

### **PRESSURE OUTPUT CHARACTERISTICS (V**<sub>DD</sub> = 3 V, T = 25°C UNLESS OTHERWISE NOTED)

Parameter	Conditio	ns	Min.	Тур.	Max	Unit
Operating Pressure Range	Prange	Full Accuracy	0		7	bar
Absolute Accuracy, autozero at one pressure point 4001100 mbar	at 060°0	C, 4001100 mbar	-4.5		+4.5	mbar
Absolute Accuracy, autozero at one pressure point 4007000 mbar	at 04	0°C, 07000 mbar	-50		+50	mbar
Maximum error with supply voltage (1)	V <sub>DD</sub> = 2.2	2 V 3.6 V		±3		mbar
Long-term stability				±1		mbar/yr
	OSR	4096		0.034		
		2048		0.048		
Resolution RMS		1024		0.067		mbar
		512		0.097		
		256		0.176		

(1) With autozero at 3V point

# TEMPERATURE OUTPUT CHARACTERISTICS ( $V_{DD}$ = 3 V, T = 25°C UNLESS OTHERWISE NOTED)

Parameter	Conditions		Min.	Тур.	Max	Unit
Absolute Accuracy 4001100mbar	040°C		-1		+1	°C
Absolute Accuracy 4001100mbar	-2085°C		-2		+2	°C
Absolute Accuracy 400 7000mbar	-2085°C		-3		+3	°C
Maximum error with supply voltage (1)	$V_{DD} = 2.2 V \dots 3.6 V$			±0.2		°C
	OSR	4096		0.002		
		2048		0.003		
Resolution RMS		1024		0.005		°C
		512		0.008		
		256		0.012		

(1) With autozero at 3V point



# **PERFORMANCE SPECIFICATIONS (CONTINUED)**

### DIGITAL INPUTS (PS, CSB, DIN, SCLK, SDA, SCL)

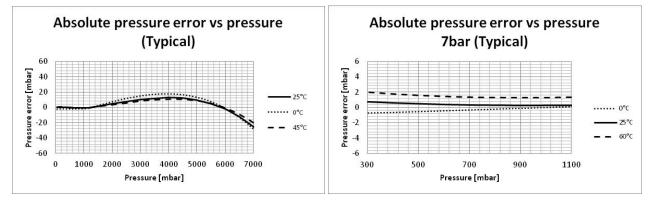
Parameter	Symbol	Conditions	Min.	Тур.	Max	Unit
Serial data clock	SCLK	SPI protocol			20	MHz
Serial data clock	SCL	I2C protocol			400	kHz
Input high voltage	VIH	Pins CSB	80% V <sub>DD</sub>		100% V <sub>DD</sub>	V
Input low voltage	V <sub>IL</sub>		0% V <sub>DD</sub>		20% V <sub>DD</sub>	V
Input leakage current	I <sub>leak25°C</sub>	at 25°c			0.15	μA

### DIGITAL OUTPUTS (DOUT, SDA, SCL)

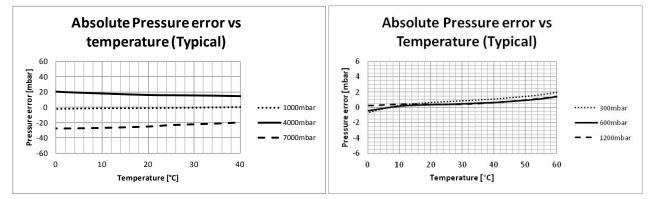
Parameter	Symbol	Conditions	Min.	Тур.	Max	Unit
Output high voltage	V <sub>OH</sub>	I <sub>source</sub> = 0.6 mA	80% V <sub>DD</sub>		100% V <sub>DD</sub>	V
Output low voltage	V <sub>OL</sub>	I <sub>sink</sub> = 0.6 mA	0% V <sub>DD</sub>		20% V <sub>DD</sub>	V
Load capacitance	CLOAD			16		pF

# PERFORMANCE CHARACTERISTICS

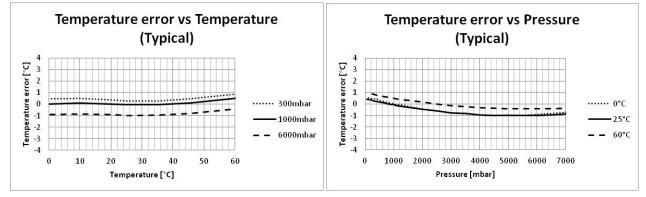
### PRESSURE ERROR VS PRESSURE



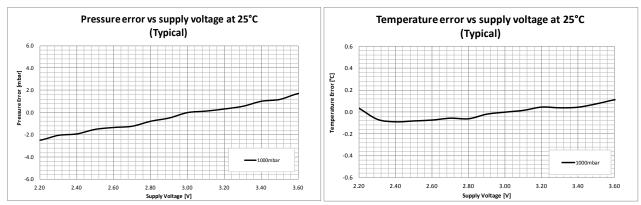
### PRESSURE ERROR VS TEMPERATURE



#### **TEMPERATURE ERROR VS TEMPERATURE AND PRESSURE**



### PRESSURE AND TEMPERATURE ERROR VS POWER SUPPLY





### FUNCTIONAL DESCRIPTION

#### GENERAL

The MS5803-07BA consists of a piezo-resistive sensor and a sensor interface IC. The main function of the MS5803-07BA is to convert the uncompensated analogue output voltage from the piezo-resistive pressure sensor to a 24-bit digital value, as well as providing a 24-bit digital value for the temperature of the sensor.

#### FACTORY CALIBRATION

Every module is individually factory calibrated at two temperatures and two pressures. As a result, 6 coefficients necessary to compensate for process variations and temperature variations are calculated and stored in the 128-bit PROM of each module. These bits (partitioned into 7 coefficients W1 to W7) must be read by the microcontroller software and used in the program converting D1 and D2 into compensated pressure and temperature values.

The coefficient W0 is for factory configuration and W7 contains CRC and high pressure range compensation parameters.

#### SERIAL INTERFACE

The MS5803-07BA has built in two types of serial interfaces: SPI and I<sup>2</sup>C. Pulling the Protocol Select pin PS to low selects the SPI protocol, pulling PS to high activates the I<sup>2</sup>C bus protocol.

Pin PS	Mode	Pins used
High	l <sup>2</sup> C	SDA, SCL, CSB
Low	SPI	SDI, SDO, SCLK, CSB

#### SPI MODE

The external microcontroller clocks in the data through the input SCLK (Serial CLocK) and SDI (Serial Data In). In the SPI mode module can accept both mode 0 and mode 3 for the clock polarity and phase. The sensor responds on the output SDO (Serial Data Out). The pin CSB (Chip Select) is used to enable/disable the interface, so that other devices can talk on the same SPI bus. The CSB pin can be pulled high after the command is sent or after the end of the command execution (for example end of conversion). The best noise performance from the module is obtained when the SPI bus is quiet and without communication to other devices during the ADC conversion in progress.

#### I<sup>2</sup>C MODE

The external microcontroller clocks in the data through the input SCL (Serial CLock) and SDA (Serial DAta). The sensor responds on the same pin SDA which is bidirectional for the  $I^2C$  bus interface. So this interface type uses only 2 signal lines and does not require a chip select, which can be favorable to reduce board space. In  $I^2C$ -Mode the complement of the pin CSB (Chip Select) represents the LSB of the  $I^2C$  address. It is possible to use two sensors with two different addresses on the  $I^2C$  bus. The pin CSB shall be connected to VDD or GND (do not leave unconnected!).

Pin CSB	Address (7 bits)
High	0x76 (1110110 b)
Low	0x77 (1110111 b)



#### COMMANDS

The MS5803-07BA has only five basic commands:

- 1. Reset
- 2. Read PROM (128 bit of calibration words)
- 3. D1 conversion
- 4. D2 conversion
- 5. Read ADC result (24 bit pressure / temperature)

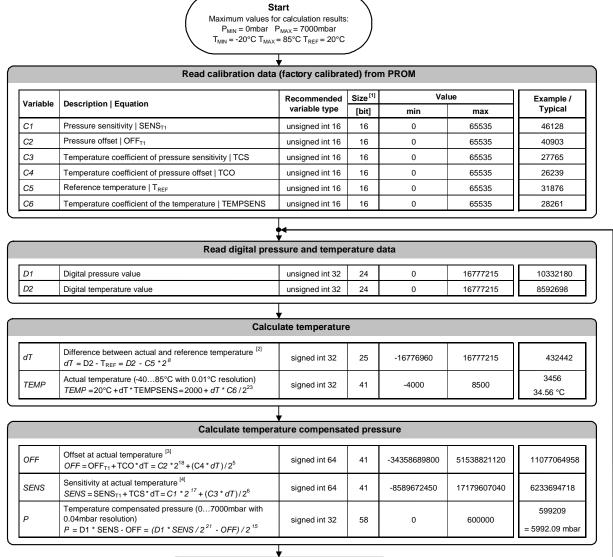
Size of each command is 1 byte (8 bits) as described in the table below. After ADC read commands the device will return 24 bit result and after the PROM read 16bit result. The address of the PROM is embedded inside of the PROM read command using the Ad2, Ad1 and Ad0 bits.

	Command byte													
Bit number	0	1	2	3	4	5	6	7						
Bit name	PR M	COV	-	Тур	Ad2/ Os2	Ad1/ Os1	Ad0/ Os0	Stop						
Command														
Reset	0	0	0	1	1	1	1	0	0x1E					
Convert D1 (OSR=256)	0	1	0	0	0	0	0	0	0x40					
Convert D1 (OSR=512)	0	1	0	0	0	0	1	0	0x42					
Convert D1 (OSR=1024)	0	1	0	0	0	1	0	0	0x44					
Convert D1 (OSR=2048)	0	1	0	0	0	1	1	0	0x46					
Convert D1 (OSR=4096)	0	1	0	0	1	0	0	0	0x48					
Convert D2 (OSR=256)	0	1	0	1	0	0	0	0	0x50					
Convert D2 (OSR=512)	0	1	0	1	0	0	1	0	0x52					
Convert D2 (OSR=1024)	0	1	0	1	0	1	0	0	0x54					
Convert D2 (OSR=2048)	0	1	0	1	0	1	1	0	0x56					
Convert D2 (OSR=4096)	0	1	0	1	1	0	0	0	0x58					
ADC Read	0	0	0	0	0	0	0	0	0x00					
PROM Read	1	0	1	0	Ad2	Ad1	Ad0	0	0xA0 to 0xAE					

Figure 1: Command structure



### PRESSURE AND TEMPERATURE CALCULATION



Display pressure and temperature value

Notes [1] [2] [3] [4]

Maximal size of intermediate result during evaluation of variable

min and max have to be defined min and max have to be defined

min and max have to be defined min and max have to be defined

Figure 2: Flow chart for pressure and temperature reading and software compensation.



# MS5803-07BA Altimeter and diving Pressure Sensor

### SECOND ORDER TEMPERATURE COMPENSATION

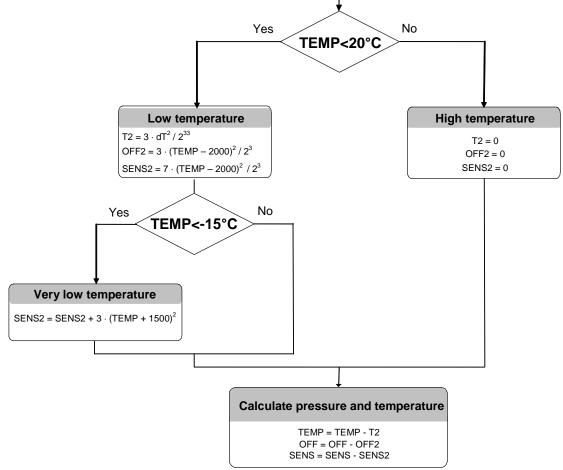


Figure 3: Flow chart for pressure and temperature to the optimum accuracy.

#### HIGH PRESSURE RANGE COMPENSATION

The last 16bits word of the PROM (Word7) is defined as follow:

			C8 (6	6 Bit)			C7 (6bit)							CRC				
Word 7	DB5	DB4	DB3	DB2	DB1	DB0	DB5	DB4	DB3	DB2	DB1	DB0	DB3	DB2	DB1	DB0		

Figure 4: Word 7, bit description.



# MS5803-07BA Altimeter and diving Pressure Sensor

The first 4 bits (bit 0 to 3) of word 7 correspond to the checksum, the 6 following bits (bit 4 to 9) correspond to the C7 coefficient and the 6 last bits (bit 10 to 15) correspond to C8 coefficient. When defining P and T as the pressure and temperature issued from the pressure and temperature calculation (p8), the compensated high pressure P3 is defined as follow:

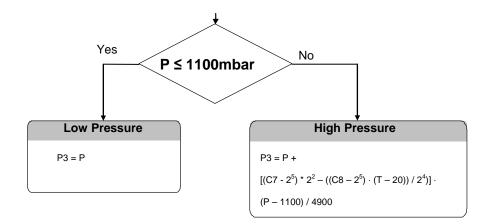


Figure 5: Flow chart for High pressure P3 calculation



# **SPI INTERFACE**

### **RESET SEQUENCE**

The Reset sequence shall be sent once after power-on to make sure that the calibration PROM gets loaded into the internal register. It can be also used to reset the device ROM from an unknown condition

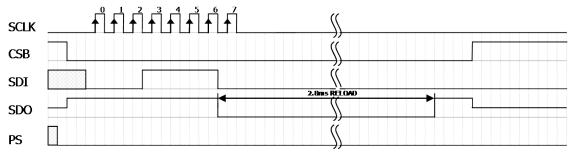
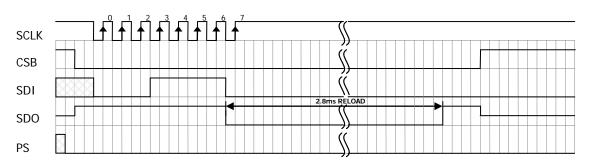
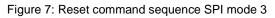


Figure 6: Reset command sequence SPI mode 0

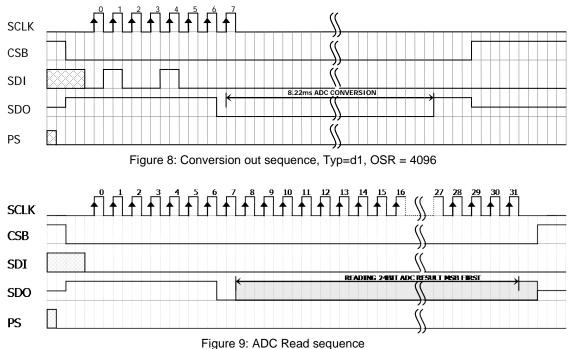






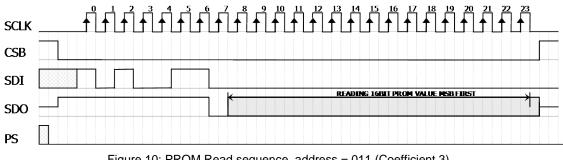
#### CONVERSION SEQUENCE

The conversion command is used to initiate uncompensated pressure (D1) or uncompensated temperature (D2) conversion. The chip select can be disabled during this time to communicate with other devices. After the conversion, using ADC read command the result is clocked out with the MSB first. If the conversion is not executed before the ADC read command, or the ADC read command is repeated, it will give 0 as the output result. If the ADC read command is sent during conversion the result will be 0, the conversion will not stop and the final result will be wrong. Conversion sequence sent during the already started conversion process will yield incorrect result as well.



#### PROM READ SEQUENCE

The read command for PROM shall be executed once after reset by the user to read the content of the calibration PROM and to calculate the calibration coefficients. There are in total 8 addresses resulting in a total memory of 128 bit. Address 0 contains factory data and the setup, addresses 1-6 calibration coefficients and address 7 contains the serial code and CRC. The command sequence is 8 bits long with a 16 bit result which is clocked with the MSB first.





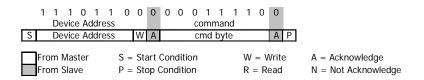
# I<sup>2</sup>C INTERFACE

#### COMMANDS

Each  $I^2C$  communication message starts with the start condition and it is ended with the stop condition. The MS5803-07BA address is 111011Cx, where C is the complementary value of the pin CSB. Since the IC does not have a microcontroller inside, the commands for  $I^2C$  and SPI are quite similar.

#### **RESET SEQUENCE**

The reset can be sent at any time. In the event that there is not a successful power on reset this may be caused by the SDA being blocked by the module in the acknowledge state. The only way to get the MS5803-07BA to function is to send several SCLKs followed by a reset sequence or to repeat power on reset.



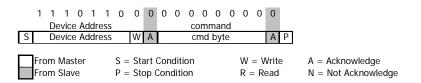


#### **CONVERSION SEQUENCE**

A conversion can be started by sending the command to MS5803-07BA. When command is sent to the system it stays busy until conversion is done. When conversion is finished the data can be accessed by sending a Read command, when an acknowledge appears from the MS5803-07BA, 24 SCLK cycles may be sent to receive all result bits. Every 8 bit the system waits for an acknowledge signal.

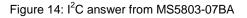
	1 1 1 0 1 1 0 0 0 0 1 0 0 1 0 0 0 0 Device Address command																						
S	Device Address W A cmd byte A P																						
	Fro Fro	om om	Mas Slav	ster /e			S = P =											Vrite ead		A = A N = M		5	е

Figure 12: I<sup>2</sup>C Command to initiate a pressure conversion (OSR=4096, typ=D1)





1	I 1 De			1 ddre		0	1	0	Х	Х	Х	X da		Х	Х	Х	0	Х	Х	Х	X da		Х	Х	Х	0	Х	Х	Х		X ata	Х	Х	Х	0
S	De	evic	e A	ddre	SS		R	Α			Da	ita :	23-	16			Α			Da	ita	15 -	- 8			А			D	ata	7 -	0			ΝP
From Master S = Start From Slave P = Stop														= V = R(								edg now		ge											





#### PROM READ SEQUENCE

The PROM Read command consists of two parts. First command sets up the system into PROM read mode. The second part gets the data from the system.

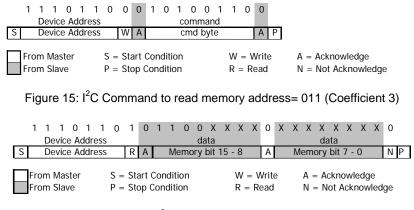


Figure 16: I<sup>2</sup>C answer from MS5803-07BA

# CYCLIC REDUNDANCY CHECK (CRC)

MS5803-07BA contains a PROM memory with 128-Bit. A 4-bit CRC has been implemented to check the data validity in memory.

A d d	D B 1 5	D B 1 4	D B 1 3	D B 1 2	D B 1	D B 1 0	D B 9	D B 8	D B 7	D B 6	D B 5	D B 4	D B 3	D B 2	D B 1	D B 0
0		16 bit reserved for manufacturer														
1	C1 (16 bit unsigned)															
2	C2 (16 bit unsigned)															
3		C3 (16 bit unsigned)														
4		C4 (16 bit unsigned)														
5		C5 (16 bit unsigned)														
6		C6 (16 bit unsigned)														
7		C8 (6bits) C7 (6bits) CRC														

Figure 17: Memory PROM mapping

C Code example for CRC-4 calculation:

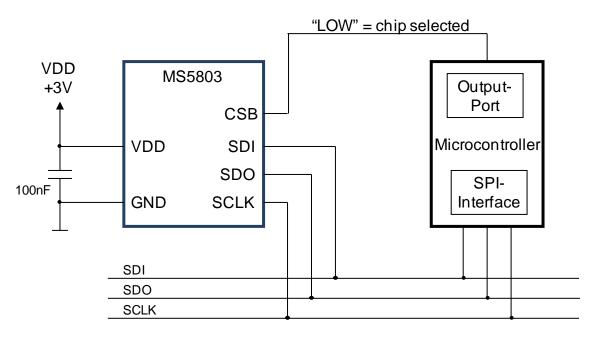
```
unsigned char crc4(unsigned int n_prom[])
int cnt;
                                                                      // simple counter
unsigned int n_rem=0;
                                                                      // crc reminder
unsigned char n_bit;
          n_prom[7]=((n_prom[7]) & 0xFFF0);
                                                                      // CRC byte is replaced by 0
          for (cnt = 0; cnt < 16; cnt++)
                                                                      // operation is performed on bytes
                                                                      // choose LSB or MSB
                    if (cnt%2==1)
                                        n_rem ^= (unsigned short) ((n_prom[cnt>>1]) & 0x00FF);
                                        n_rem ^= (unsigned short) (n_prom[cnt>>1]>>8);
                    else
                    for (n_bit = 8; n_bit > 0; n_bit--)
                              if (n_rem & (0x8000))
                                                            n_{rem} = (n_{rem} << 1) ^ 0x3000;
                                                            n_rem = (n_rem << 1);
                              else
                              }
          n_rem= ((n_rem >> 12) & 0x000F);
                                                                      // final 4-bit reminder is CRC code
          return (n_rem ^ 0x00);
}
```



# **APPLICATION CIRCUIT**

The MS5803-07BA is a circuit that can be used in conjunction with a microcontroller in mobile altimeter applications. It is designed for low-voltage systems with a supply voltage of 3 V.

### **SPI protocol communication**



# I<sup>2</sup>C protocol communication

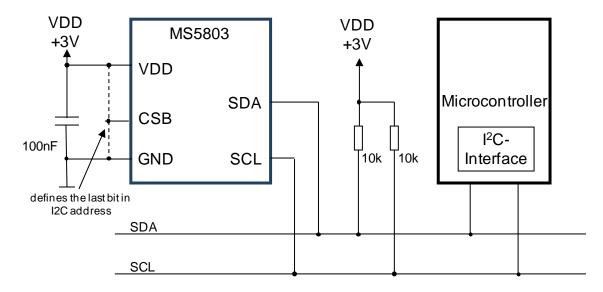


Figure 18: Typical application circuit with SPI / I<sup>2</sup>C protocol communication



# PACKAGE OUTLINE AND PIN CONFIGURATION

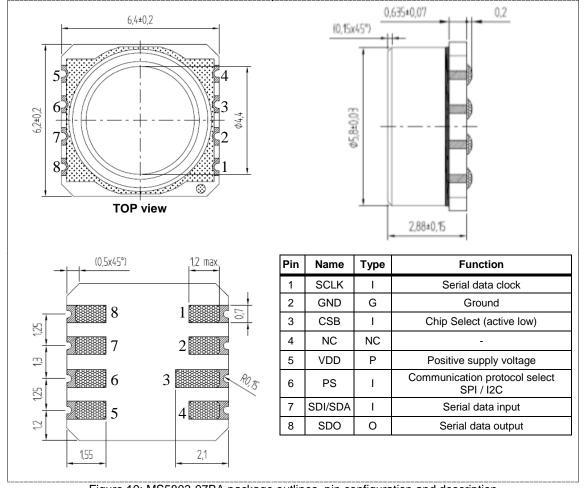


Figure 19: MS5803-07BA package outlines, pin configuration and description

(1) Dimensions in mm Notes:

(2) General tolerance ±0.1

(3) Cap centering  $\pm$  0.15 from center of the ceramic

# **RECOMMENDED PAD LAYOUT**

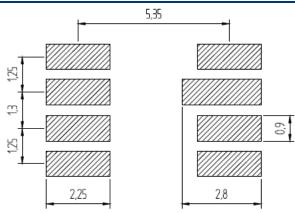


Figure 20: MS5803-07BA recommended pad layout



# SHIPPING PACKAGE

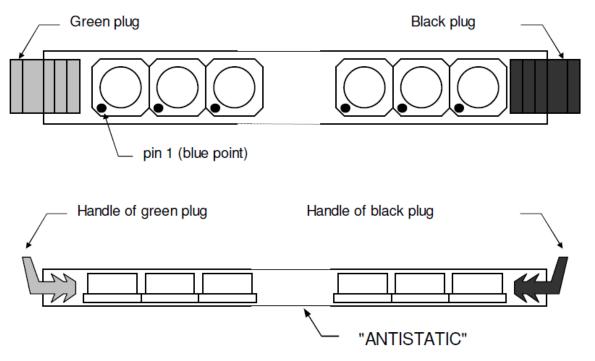
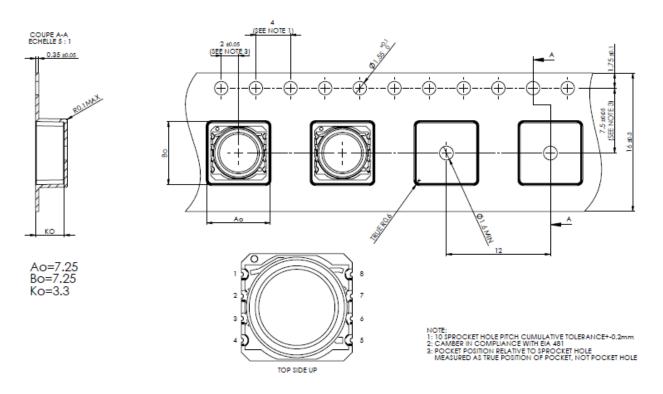
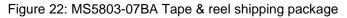


Figure 21: MS5803-07BA tube shipping package







### MOUNTING AND ASSEMBLY CONSIDERATIONS

#### SOLDERING

Please refer to the application note AN808 available on our website for all soldering issues.

#### MOUNTING

The MS5803-07BA can be placed with automatic Pick & Place equipment using vacuum nozzles. It will not be damaged by the vacuum. Due to the low stress assembly the sensor does not show pressure hysteresis effects. It is important to solder all contact pads.

#### CONNECTION TO PCB

The package outline of the module allows the use of a flexible PCB for interconnection. This can be important for applications in watches and other special devices.

#### SEALING WITH O-RINGS

In products like outdoor watches the electronics must be protected against direct water or humidity. For those products the MS5803-07BA provides the possibility to seal with an O-ring. The protective cap of the MS5803-07BA is made of special anticorrosive stainless steel with a polished surface. In addition to this the MS5803-07BA is filled with silicone gel covering the sensor and the bonding wires. The O-ring (or O-rings) shall be placed at the outer diameter of the metal cap. This method avoids mechanical stress because the sensor can move in vertical direction.

#### CLEANING

The MS5803-07BA has been manufactured under cleanroom conditions. It is therefore recommended to assemble the sensor under class 10'000 or better conditions. Should this not be possible, it is recommended to protect the sensor opening during assembly from entering particles and dust. To avoid cleaning of the PCB, solder paste of type "no-clean" shall be used. Cleaning might damage the sensor!

#### ESD PRECAUTIONS

The electrical contact pads are protected against ESD up to 2 kV HBM (human body model). It is therefore essential to ground machines and personnel properly during assembly and handling of the device. The MS5803-07BA is shipped in antistatic transport boxes. Any test adapters or production transport boxes used during the assembly of the sensor shall be of an equivalent antistatic material.

#### **DECOUPLING CAPACITOR**

Particular care must be taken when connecting the device to the power supply. A minimum 100 nF ceramic capacitor must be placed as close as possible to the MS5803-07BA VDD pin. This capacitor will stabilize the power supply during data conversion and thus, provide the highest possible accuracy.

### **ORDERING INFORMATION**

Part Number / Article Number	Product	Delivery Form		
MS580307BA06-00	MS5803-07BA Double Range Pressure Sensor	Tube		
MS580307BA06-50	MS5803-07BA Double Range Pressure Sensor T&R	Tape and Reel		

### **FACTORY CONTACTS**

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